

A<sup>2</sup> 34. (Amended) An apparatus for producing semiconductor devices comprising a molten-solder vessel arranged so that gold bump elements provided on the electrodes of a semiconductor element can be immersed in said vessel, and a support structure for hanging said semiconductor element, said support structure including a hanging mechanism comprising at least two mutually movably coupled coupling members so that the semiconductor element can float on the molten solder.

A<sup>3</sup> 37. (Amended) An apparatus for producing semiconductor devices comprising a molten-solder vessel arranged so that gold bump elements provided on the electrodes of a semiconductor element can be immersed in said vessel, and a support structure for holding said semiconductor element, said support structure including a holding mechanism comprising at least two mutually movably coupled coupling members so that the semiconductor element can float on the molten solder and a pump-type adsorption head having an open suction hole for holding the semiconductor element.